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Paper Submission: <https://edas.info/N26003> or Login EDAS at <http://edas.info/> by selecting "CyberC 2019".
Electronic submission to Papers@cyberc.org with a title of "CyberC 2019 Submission" is also accepted.

Become a sponsor, contact:

Chi-Ming Chen at chimingchen@ieee.org

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SPECIAL ISSUES

You can submit an extended paper version to Journal of [Sensors](http://www.mdpi.com/journal/sensors) by MDPI. The submission could be **all the time before** December 30 2019: First submitted, first reviewed, and first published.

EVENTS

Emerging Technology Summit: October 18, 2019.

PRELIMINARY CALL FOR PAPERS

CyberC 2019

The 11th Int. Conference on Cyber-Enabled Distributed Computing and Knowledge Discovery

Guilin, China, October 17 - 19, 2019, www.Cyberc.org

2019 Theme: Intelligent Cyberspace via the Convergence of AI, Big Data, 5G and Beyond

Technical Co-sponsors: IEEE, IEEE Computer Society, IEEE TCSIM (Technical Committee on Simulation), IEEE Communications Society (ComSoc) Technical Committee on Big Data (TCBD)

Organizer: Guilin University of Electronic Technology

Co-hosted by: Nanjing University of Posts & Telecommunications, Zhengzhou University, Pengcheng Laboratory

Sponsored by: Huawei, AT&T, InfoBeyond, Tech Mahindra

Publication: IEEE (EI & Explore), EI, Journal of [Sensors](http://www.ieee.org) (Special issue)

Scopes: CyberC promotes in-depth exploration of the most recent research and developments in the fields of AI, big data, distributed computing, clouds, cyber security, pervasive computing, mobile computing, Internet of Things, and other cyber-based technologies. Professors, scientists, engineers, and students in these areas are encouraged to participate. CyberC also welcomes industrial participations.

Submission: [EDAS: edas.info/N26003](https://edas.info/N26003) or Email: Papers@CyberC.org

Venue: 2019 CyberC will be held in Guilin – A natural beautiful city in China.

Summits: CyberC 2019 co-hosts **Emerging Technology Summit (AI, Big Data, 5G)** forum that emphasizes innovative and state-of-art R&D, industry products, specifications, showcases, tutorial, technical transitions, and markets.

Topics: The topics of interests include, but not limited to:

- Cyber network and Cybersecurity
- Big Data, AI and Machine Learning
- Internet of things, localization, and distributed computing
- Blockchain theory and applications
- 5G and mobile computing
- Cybersecurity and network monitoring
- Signaling processing and wireless Communications
- Cyber surveillance and cyber physical systems
- Cloud Computing and mobile services
- HPC and Distributed Computing

- Sensors, ICS, Power grids, and communications
- Cyber security and privacy, cyber trust, cyber agility, and cyber assurance

Co-hosted Workshops: CyberC 2019 incorporates several workshops:

- **Big Data & AI 2019:** The 6th International Workshop on Big Data and Artificial Intelligence
- **Security 2019:** The 7th workshop on Cyber Security and Privacy
- **Blockchain 2019:** The first workshop on Blockchain
- **IOT 2019:** The 3rd International Workshop on Internet of Things and Future Communication Technologies

INFORMATION FOR AUTHORS

The CyberC 2019 Proceedings will be published by IEEE CPS. **Full papers** for CyberC 2019 must not exceed 10 pages of IEEE 2-column format, while **short papers** must not exceed 4 pages. Please visit the conference web site at <http://www.cyberc.org> for precise formatting and submission instructions.

IMPORTANT DATES

Submission deadline for full (10-page) and/or short (4-page) papers: **May 10, 2019**
Notification of acceptance: **July 20, 2019**
Camera-ready deadline: **August 20, 2019**

SPECIAL ISSUE

<http://cyberc.org/Callforpapers/SpecialIssue>

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CyberC 2018: Number of submissions: 246, Number of full papers: 70, Number of Short Papers: 30, Number of Reviewers: 165, Number of Attendees: 130, Number of Sessions: 10, Number of Keynotes: 12, Scholars in CyberC QQ group: 331, Scholars in Big Data QQ group: 489.

CyberC QQ Group: 426380304; **Big Data Group:** 208385582

CyberC 2009 - 2018 Proceeding (Accepted papers): [EI](http://www.ieee.org), [IEEE Xplore](http://www.ieee.org), [Google Scholar](http://www.google.com), [Scopus](http://www.scopus.com), [DBLP](http://www.dbpl.com)